

FEATURES

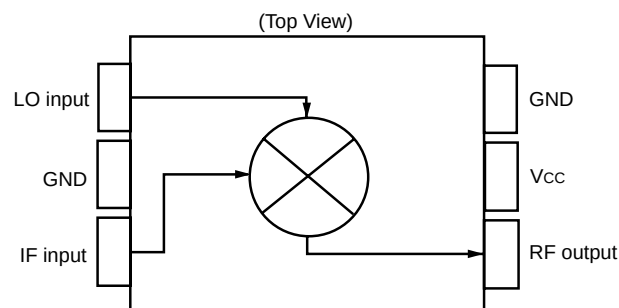
- **HIGH OUTPUT FREQUENCY:**
 $f_{RFout} = 0.8$ to 2.5 GHz
- **SUPPLY VOLTAGE:**
 $V_{CC} = 2.7$ to 3.3 V
- **HIGH IP₃ AND CONVERSION GAIN:**
OIP₃ = +10 dBm typ at $f_{RFout} = 0.9$ GHz
CG = +11 dBm typ at $f_{RFout} = 0.9$ GHz
- **HIGH-DENSITY SURFACE MOUNTING:**
6-pin super minimold package

DESCRIPTION

The UPC8187TB is a silicon monolithic integrated circuit designed as a frequency up-converter for wireless transceivers. This IC has higher operating frequency, lower distortion and higher conversion gain than the conventional UPC8163TB. This device is manufactured using NEC's 30 GHz f_{max} UHS0 (Ultra High Speed Process) silicon bipolar process.

NEC's stringent quality assurance and test procedures ensure the highest reliability and performance.

BLOCK DIGRAM



APPLICATIONS

- TDMA, PCS, CDMA
- Digital Cellular/Cordless Phones
- Wireless Tranceivers

ELECTRICAL CHARACTERISTICS

($T_A = 25^\circ\text{C}$, $V_{CC} = V_{RFOUT} = 2.8$ V, $f_{IFin} = 150$ MHz, $P_{LOin} = -5$ dBm)

PART NUMBER PACKAGE OUTLINE				UPC8187TB S06		
SYMBOLS	PARAMETERS AND CONDITIONS ¹		UNITS	MIN	TYP	MAX
I _{CC}	Circuit Current (no signal)		mA	11	15	19
CG ₁	Conversion Gain,	$f_{RFout} = 0.83$ GHz, $P_{IFin} = -20$ dBm	dB	8	11	14
CG ₂		$f_{RFout} = 1.9$ GHz, $P_{IFin} = -20$ dBm	dB	8	11	14
CG ₃		$f_{RFout} = 2.4$ GHz, $P_{IFin} = -20$ dBm	dB	7	10	13
P _{O(SAT)1}	Saturated RF Output Power,	$f_{RFout} = 0.83$ GHz, $P_{IFin} = 0$ dBm	dBm	+1.5	+4	—
P _{O(SAT)2}		$f_{RFout} = 1.9$ GHz, $P_{IFin} = 0$ dBm	dBm	0	+2.5	—
P _{O(SAT)3}		$f_{RFout} = 2.4$ GHz, $P_{IFin} = 0$ dBm	dBm	-1.5	+1	—
OIP ₃₁	Output Third-Order Distortion Intercept Point, $f_{RFout} = 0.83$ GHz		$f_{IFin1} = 150$ MHz	dBm	—	10
OIP ₃₂			$f_{IFin2} = 151$ MHz	dBm	—	10
OIP ₃₃				dBm	—	8.5
IIP ₃₁	Input Third-Order Distortion Intercept Point, $f_{RFout} = 0.83$ GHz		$f_{IFin1} = 150$ MHz	dBm	—	-1.0
IIP ₃₂			$f_{IFin2} = 151$ MHz	dBm	—	-1.0
IIP ₃₃				dBm	—	-1.5
SSB•NF ₁	SSB Noise Figure,	$f_{RFout} = 0.83$ GHz	dB	—	11	—
SSB•NF ₂		$f_{RFout} = 1.9$ GHz	dB	—	12	—
SSB•NF ₃		$f_{RFout} = 2.4$ GHz	dB	—	12.5	—

Note:

1. $f_{RFout} < f_{LOin}$ @ $f_{RFout} = 0.83$ GHz
 $f_{LOin} < f_{RFout}$ @ $f_{RFout} = 1.9$ GHz/2.4 GHz

UPC8187TB

ABSOLUTE MAXIMUM RATINGS¹

(T_A = +25°C unless otherwise specified)

SYMBOLS	PARAMETERS	UNITS	RATINGS
V _{CC}	Supply Voltage	V	3.6
P _D	Power Dissipation ²	mW	270
T _A	Operating Ambient Temperature	°C	-40 to +85
T _{STG}	Storage Temperature	°C	-55 to +150
P _{IN}	Maximum Input Power	dBm	+10

Notes:

- Operation in excess of any one of these conditions may result in permanent damage.
- Mounted on a double-sided copper clad 50x50x1.6 mm epoxy glass PWB, T_A = +85°C.

RECOMMENDED OPERATING CONDITIONS

SYMBOLS	PARAMETERS	UNITS	MIN	TYP	MAX
V _{CC}	Supply Voltage ¹	V	2.7	2.8	3.3
T _A	Operating Ambient Temperature	°C	-40	+25	+85
P _{LOin}	Local Input Level ²	dBm	-10	-5	0
f _{RFout}	RF Output Frequency ³	GHz	0.8	—	2.5
f _{IFin}	IF Input Frequency	MHz	50	—	400

Notes:

- Same voltage applied to pins 5 and 6.
- Z_s = 50 (without matching).
- With external matching circuit.

SERIES PRODUCTS¹ (T_A = +25°C, V_{CC} = V_{PS} = V_{RFout} = 3.0 V, Z_S = Z_L = 50)

Part Number	I _{CC} (mA)	f _{RFout} (GHz)	CG (dB)			OIP ₃ (dBm)			P _O (SAT)		
			@RF 0.9 GHz ²	@RF 1.9 GHz	@RF 2.4 GHz	@RF 0.9 GHz ²	@RF 1.9 GHz	@RF 2.4 GHz	@RF 0.9 GHz ²	@RF 1.9 GHz	@RF 2.4 GHz
UPC8187TB	15	0.8 to 2.5	11	11	10	+10	+10	+8.5	+4	+2.5	+1
UPC8106TB	9	0.4 to 2.0	9	7	—	+5.5	+2.0	—	-2	-4	—
UPC8172TB	9	0.8 to 2.5	9.5	8.5	8.0	+7.5	+6.0	+4.0	+0.5	0	-0.5
UPC8109TB	5	0.4 to 2.0	6	4	—	+1.5	-1.0	—	-5.5	-7.5	—
UPC8163TB	16.5	0.8 to 2.0	9	5.5	—	+9.5	+6.0	—	+0.5	-2	—

Notes:

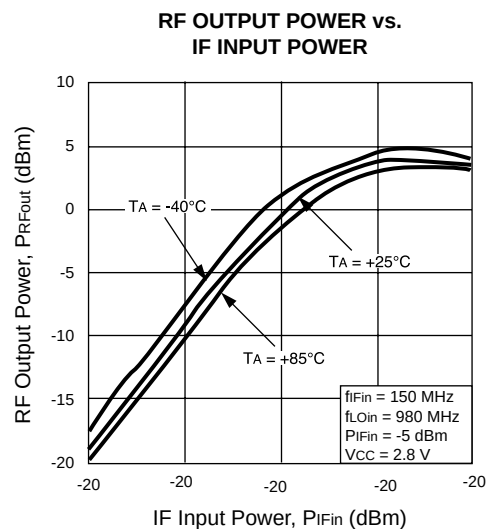
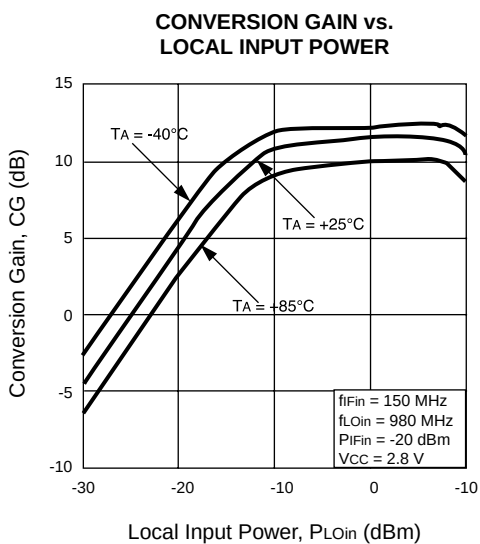
- Typical performance.
- f_{RFout} = 0.83 GHz @ UPC8163TB and UPC8187TB.

PIN FUNCTIONS (Pin Voltage is measured at V_{CC} = V_{PS} = V_{RFOUT} = 2.8V)

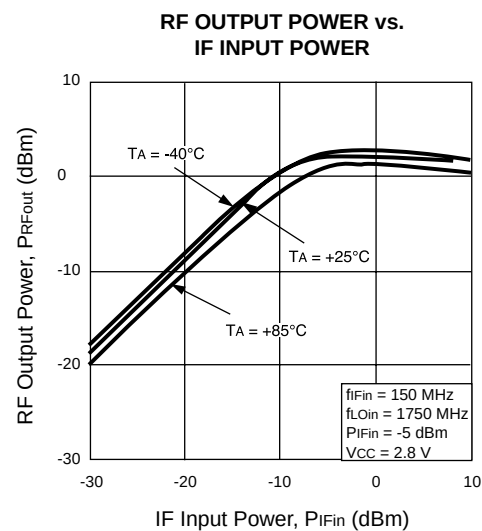
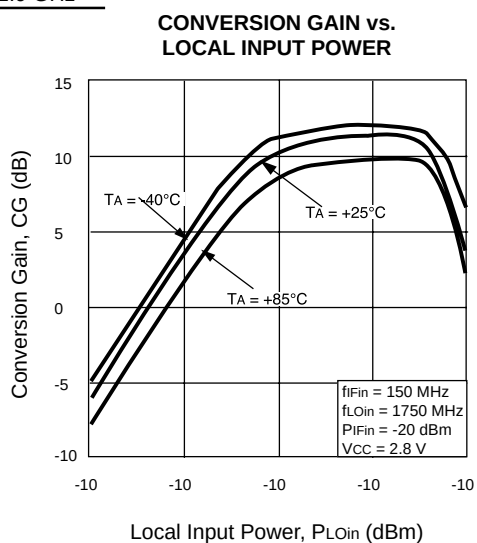
Pin No.	Pin Name	Applied Voltage (V)	Pin Voltage (V)	Function and Explanation	Equivalent Circuit
1	IFinput	—	1.2	This pin is the IF input pin to the double balanced mixer (DBM). The input is designed as a high impedance. The circuit helps suppress spurious signals. Also this symmetrical circuit can keep specified performance insensitive to process-condition distribution. For that reason, a double balanced mixer is adopted.	
2 4	GND	GND	—	GND pin. Ground pattern on the board should be formed as wide as possible. Track length should be kept as short as possible to minimize ground inductance.	
3	LOinput	—	2.1	Local input pin. Recommended input level is -10 to 0 dBm.	
5	V _{CC}	2.7 to 3.3	—	Supply voltage pin.	
6	RFoutput	Same bias as V _{CC} through external inductor	—	This pin is the RF output from the double balanced mixer. This pin is designed as an open collector. Due to the high impedance output, this pin should be externally equipped with an LC matching circuit to the next stage.	

TYPICAL PERFORMANCE CURVES (Unless otherwise specified, $T_A = 25^\circ\text{C}$)

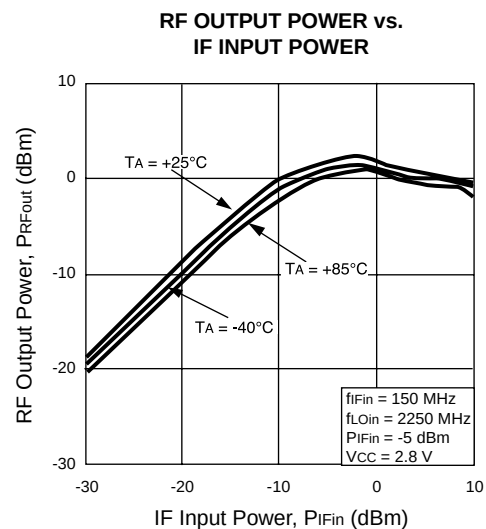
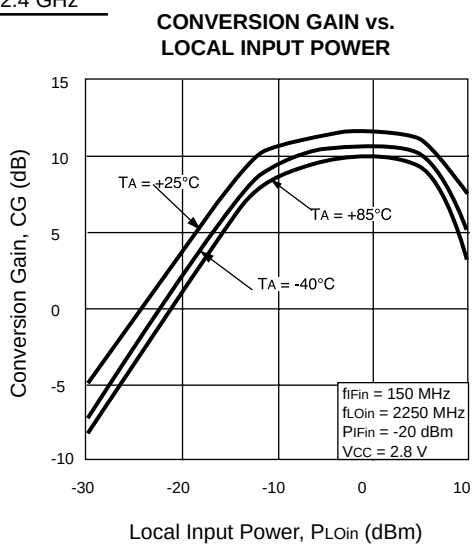
$f_{\text{RFout}} = 0.83 \text{ GHz}$



$f_{\text{RFout}} = 1.9 \text{ GHz}$

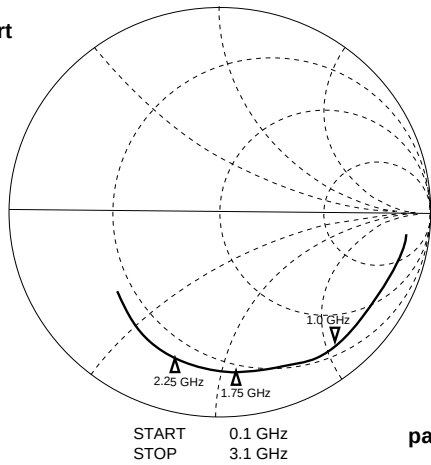


$f_{\text{RFout}} = 2.4 \text{ GHz}$

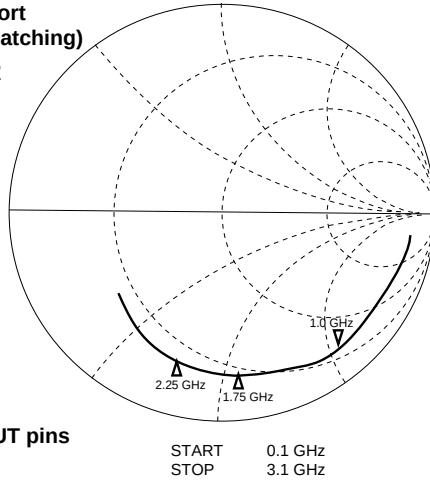


TYPICAL SCATTERING PARAMETERS (TA = 25°C)

LO port
S11

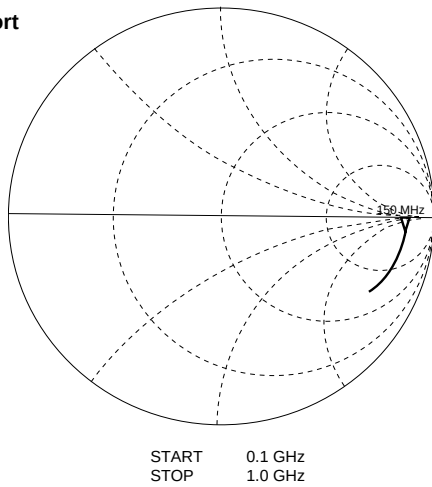


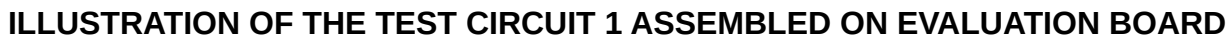
RF port
(without matching)
S22



VCC = VRFOUT = 2.8 V
parameters are monitored at DUT pins

IF port
S11





FORM	SYMBOL	VALUE
Chip Capacitor	C1, C6	100 pF
	C4	10 pF
	C2, C3	1000 pF
	C5	0.1μF
Chip Inductor	L1	12 nH
	L2	5.6nH

1. 1.5 x 1.5 x 0.028", Getek laminate, double sided copper
2. Ground pattern on rear board
3. Solder plated patterns
4. ○ Through holes

TEST CIRCUIT 2 (f_{RFout} = 1.9 GHz)

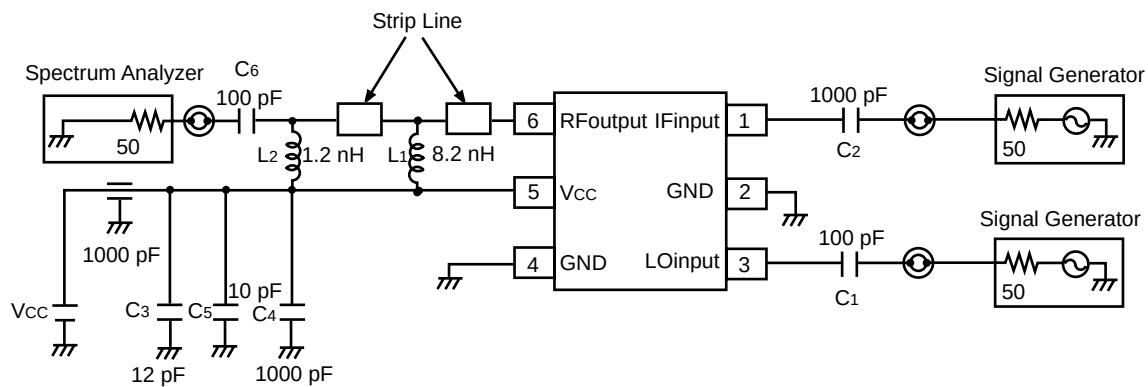
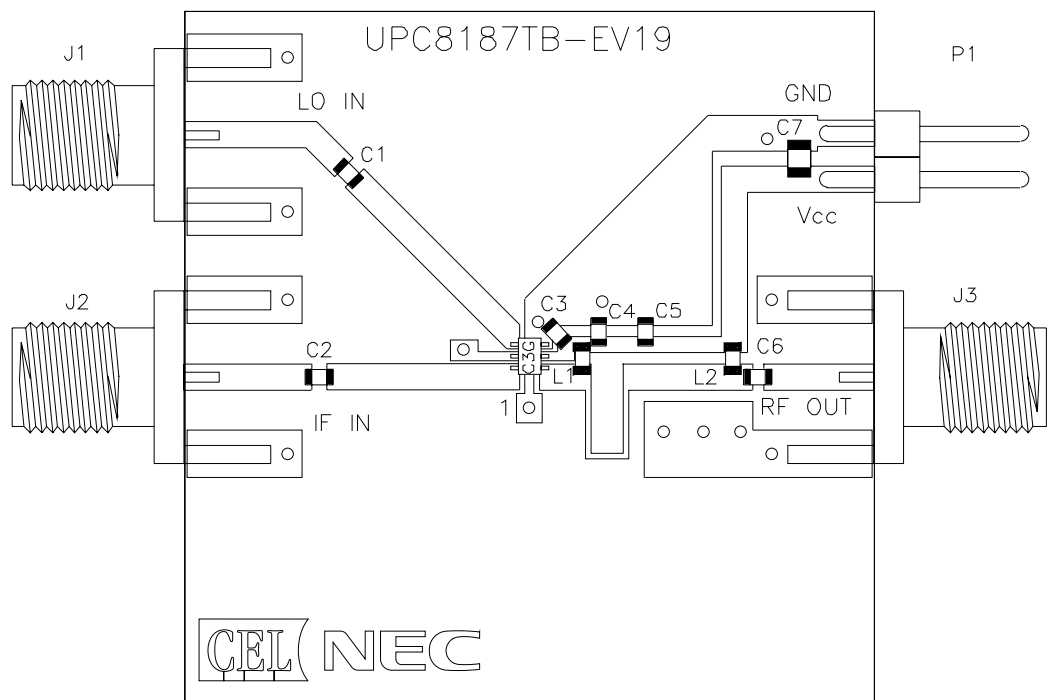


ILLUSTRATION OF TEST CIRCUIT 2 ASSEMBLED ON EVALUATION BOARD



COMPONENT LIST

FORM	SYMBOL	VALUE
Chip Capacitor	C1, C2, C4	1000 pF
	C7	0.1μF
	C6	100 pF
	C3	12 pF
	C5	10 pF
Chip Inductor	L1	8.2 nH
	L2	1.2 nH

- 1. 1.5 x 1.5 x 0.028", Getek laminate, double sided copper
- 2. Ground pattern on rear board
- 3. Solder plated patterns
- 4. ○ Through holes

TEST CIRCUIT 3 (f_{RFout} = 2.4 GHz)

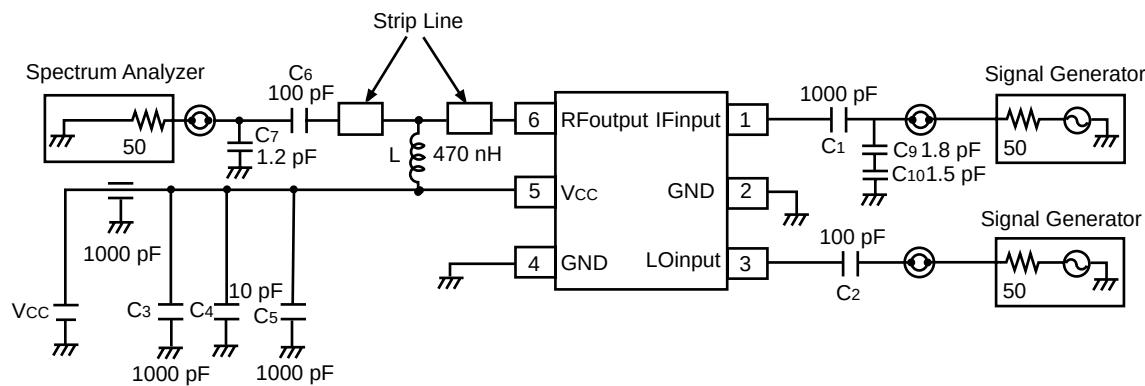
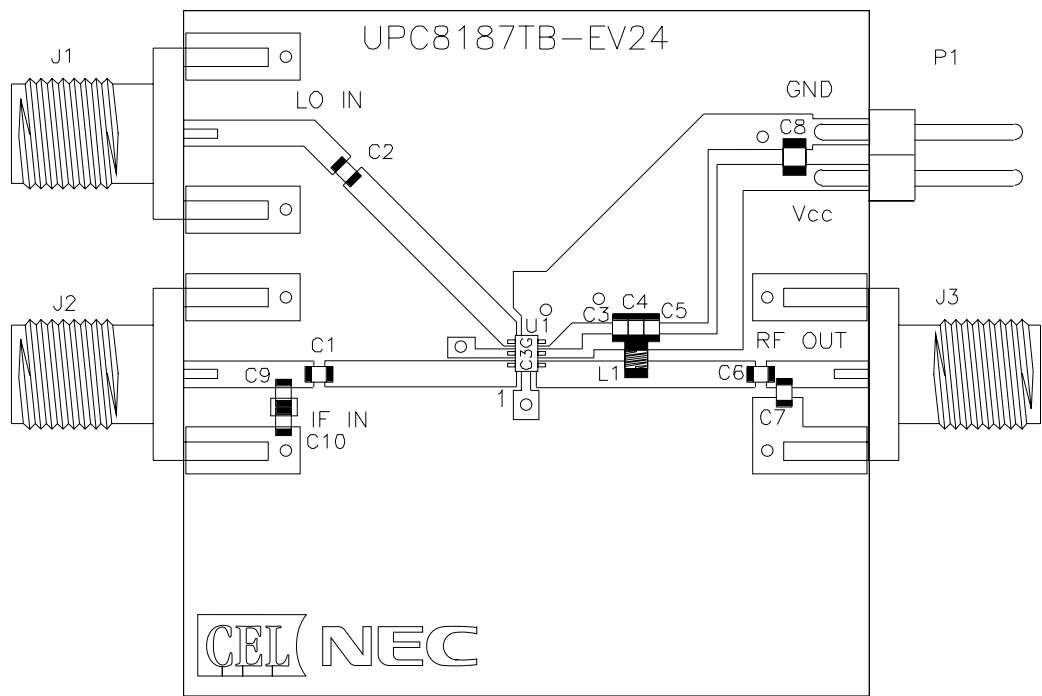


ILLUSTRATION OF TEST CIRCUIT 3 ASSEMBLED ON EVALUATION BOARD

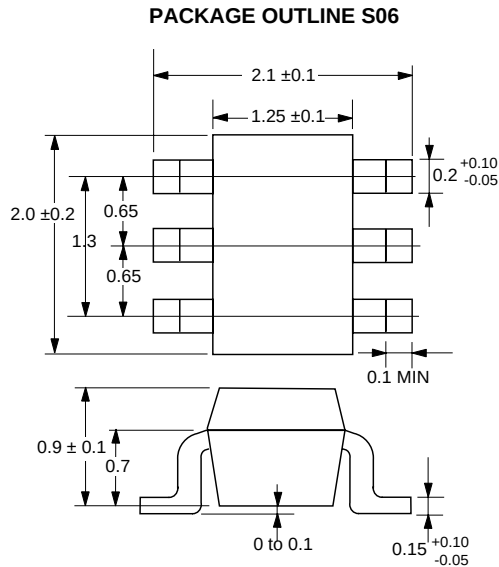


COMPONENT LIST

FORM	SYMBOL	VALUE
Chip Capacitor	C1, C3, C5	1000 pF
	C2, C6	100 pF
	C4	10 pF
	C7	1.2 pF
	C9	1.8 pF
	C10	1.5 pF
Chip Inductor	L	470 nH

1. 1.5 x 1.5 x 0.028", Getek laminate, double sided copper
2. Ground pattern on rear board
3. Solder plated patterns
4. ○ Through holes

OUTLINE DIMENSIONS (Units in mm)



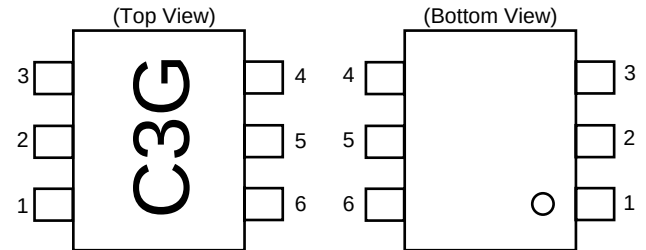
Note:
 All dimensions are typical unless otherwise specified.

ORDERING INFORMATION

Part Number	Quantity
UPC8187TB-E3	3 K pcs/reel

Note: Embossed tape, 8 mm wide. Pins 1, 2 and 3 face the tape perforation side.

PIN CONNECTIONS



PIN NO.	PIN NAME
1	IFinput
2	GND
3	LOinput
4	GND
5	Vcc
6	RFoutput

SYSTEM APPLICATION EXAMPLE (Schematic of IC location in the system)

